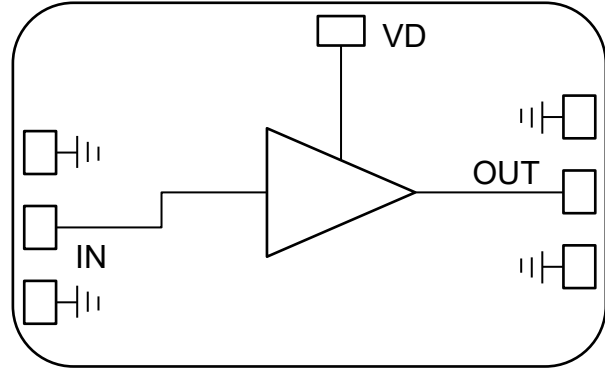


**Features**

- Single Biasing Voltage (Self Biased)
- Frequency: 2-26GHz
- Gain: 20.8dB
- Noise Figure: 2.4~5.9dB
- Input /Output Return Loss:>14.8dB/>11.3dB
- P1dB: 8.9~12.4dBm
- IP3: 21.6dBm
- Power Supply: +5 V@91 mA
- Thermal Resistance 30° C/W
- Junction Temperature 175° C
- Die Size: 3.12 x 1.38 x 0.1 mm



**Typical Applications**

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

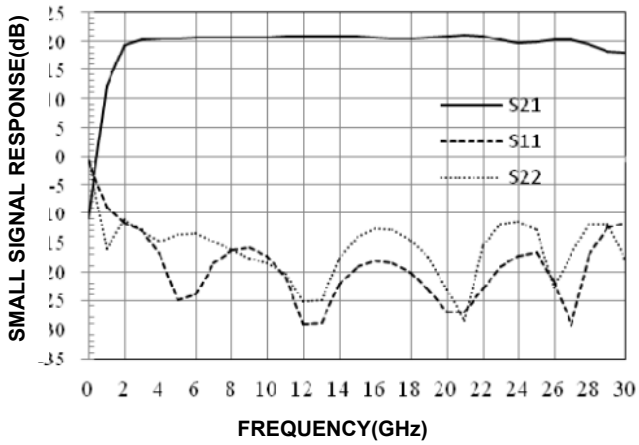
**Electrical Specifications**

TA = +25°C, Vd = +5V

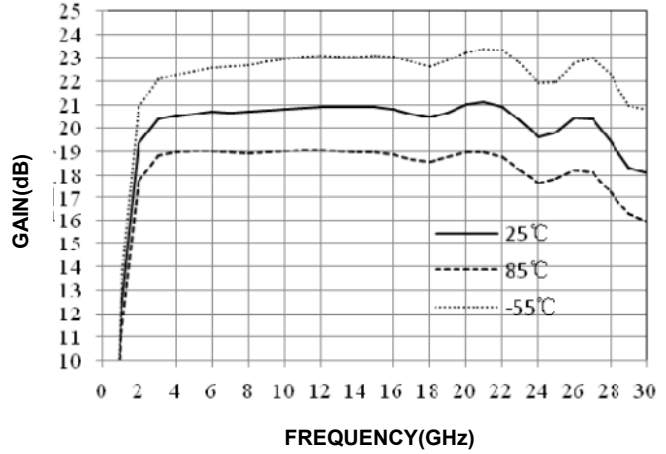


Parameters	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency	2-5			5-20			20-26			GHz
Gain	20.0	20.7	21.0	20.2	20.8	21.1	18.9	19.7	20.8	dB
Noise Figure	3.3	3.7	4.3	2.4	2.8	3.5	3.5	4.3	5.9	dB
P1dB	12.1	12.3	12.4	10.7	11.3	11.9	8.9	10.1	10.9	dBm
Input RL		14.8			17.3			19.3		dB
Output RL		11.3			14.7			14.1		dB

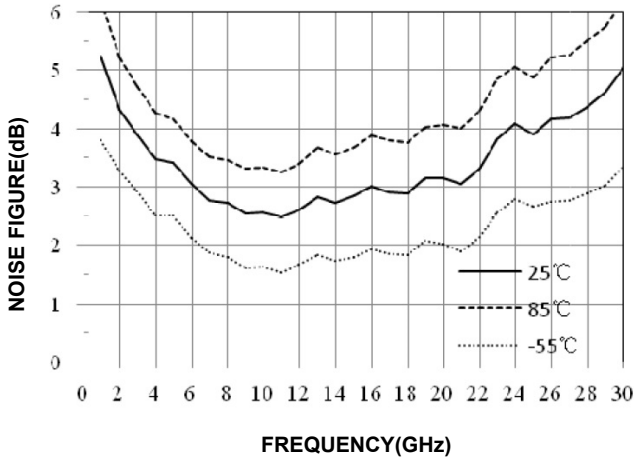
Small Signal Response (25°C)



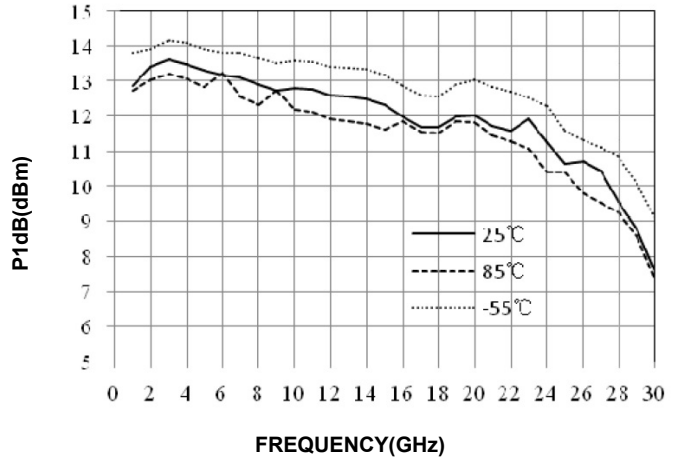
Gain vs. Temperature



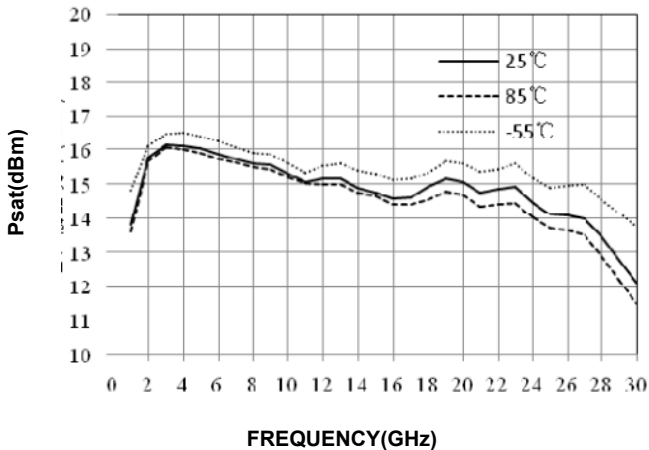
Noise Figure vs. Temperature



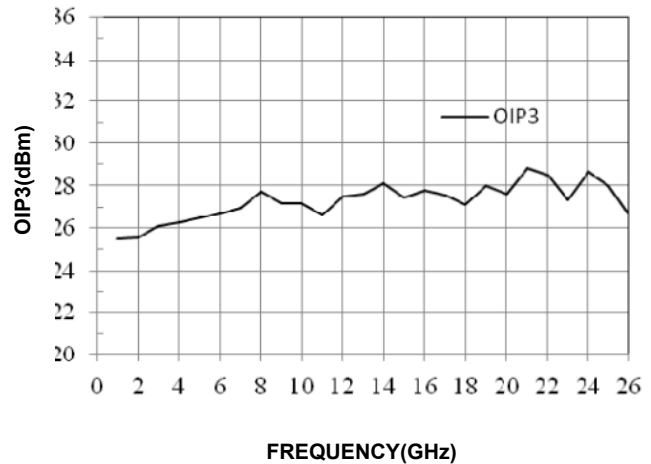
P1dB vs. Temperature



Psat vs. Temperature

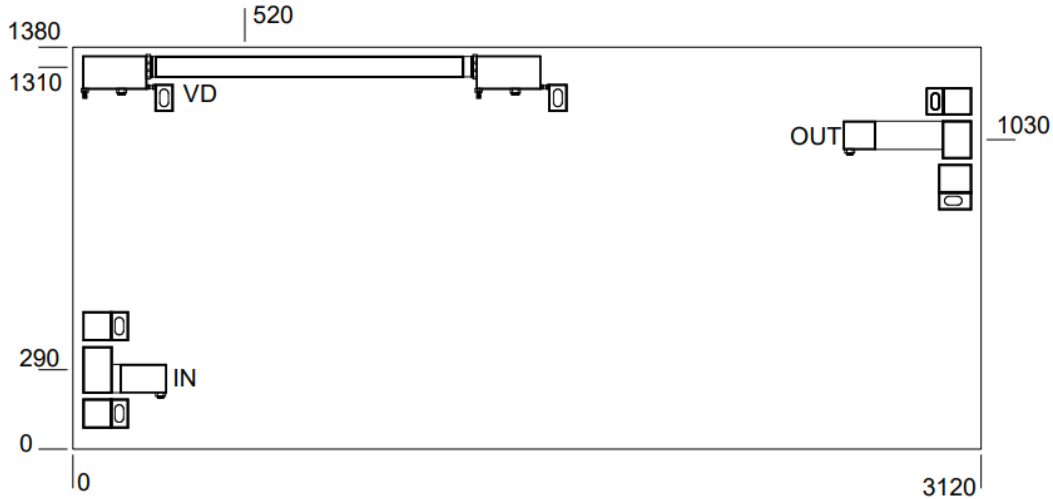


OIP3 (25°C)

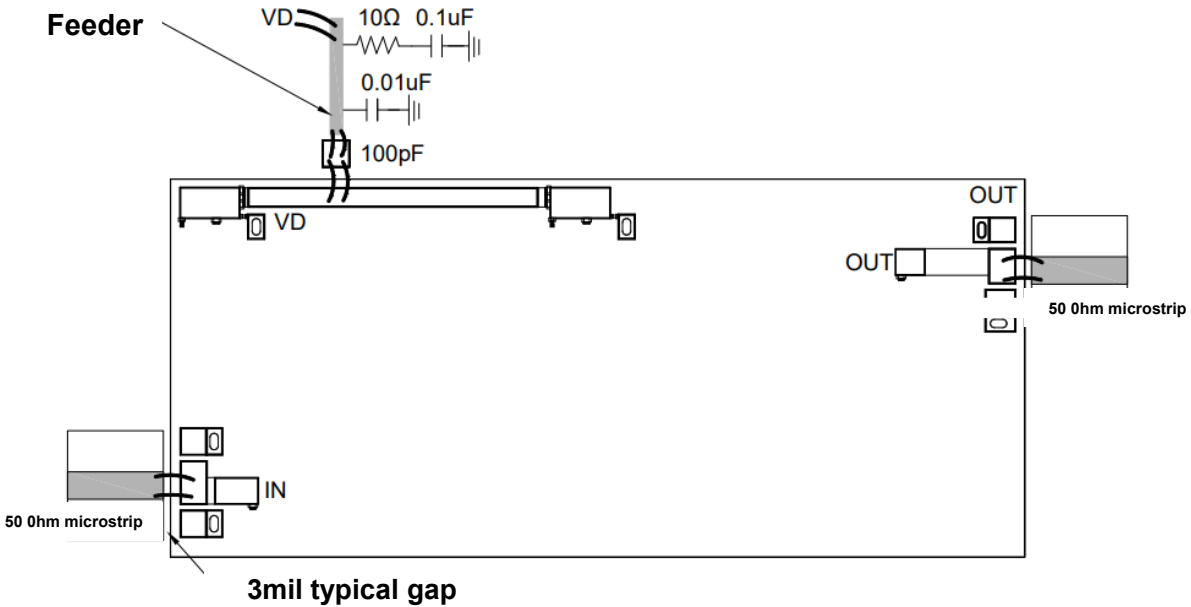




### Outline Drawing: All Dimensions in $\mu\text{m}$



### Assembly Drawing



#### Notes:

1. Die thickness: 100 $\mu\text{m}$
2. Typical bond pad is 100\*100  $\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads
7. Internal DC Block at both input and output.
8. Input/Output use two 25 $\mu\text{m}$  gold wire, length less than 250 $\mu\text{m}$  is recommended.

#### Maximum Ratings:

1. Control voltage: +9V
2. Input power: +23dBm
3. Operating temperature: -55°C to +125°C
4. Storage temperature: -65°C to +150°C